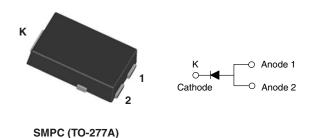
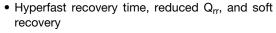


Hyperfast Rectifier, 6 A FRED Pt®



PRIMARY CHARACTERISTICS				
I _{F(AV)}	6 A			
V _R	100 V			
V _F at I _F	0.74 V			
t _{rr (typ.)}	28 ns			
T _J max.	175 °C			
Package	SMPC (TO-277A)			
Circuit configuration	Single			

FEATURES





RoHS

COMPLIANT HALOGEN

FREE

- 175 °C maximum operating junction temperature
- Specified for output and snubber operation
- Low forward voltage drop
- Low leakage current
- Meets MSL level 1, per J-STD-020, LF maximum peak of 260 °C
- Meets JESD 201 class 2 whisker test
- Material categorization: for definitions of compliance please see www.vishav.com/doc?99912

DESCRIPTION / APPLICATIONS

State of the art hyperfast recovery rectifiers specifically designed with optimized performance of forward voltage drop and hyperfast recovery time.

The planar structure and the platinum doped life time control guarantee the best overall performance, ruggedness, and reliability characteristics.

These devices are intended for use in snubber, boost, lighting, as high frequency rectifiers and freewheeling diodes.

The extremely optimized stored charge and low recovery current minimize the switching losses and reduce power dissipation in the switching element.

ABSOLUTE MAXIMUM RATINGS					
PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS	
Peak repetitive reverse voltage	V_{RRM}		100	V	
Average rectified forward current	I _{F(AV)}	T _{Sp} = 160 °C	6	۸	
Non-repetitive peak surge current	I _{FSM}	T _J = 25 °C	150	А	
Operating junction and storage temperatures	T _J , T _{Stg}		-55 to +175	°C	

ELECTRICAL SPECIFICATIONS (T _J = 25 °C unless otherwise specified)						
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Breakdown voltage, blocking voltage	V_{BR} , V_{R}	I _R = 100 μA	100	-	-	
Compared violence	V	I _F = 6 A	-	0.87	0.94	V
Forward voltage	V _F	I _F = 6 A, T _J = 125 °C	-	0.74	0.8	
Reverse leakage current		V _R = V _R rated	-	-	2	
Reverse leakage current	T _J = 125 °C, V _R = V _R rated	-	2	15	μΑ	
Junction capacitance	C _T	V _R = 100 V	-	43	-	pF



DYNAMIC RECOVERY CHARACTERISTICS (T _J = 25 °C unless otherwise specified)							
PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNITS
		$I_F = 1 \text{ A, } dI_F/dt = 50 \text{ A/}\mu\text{s, } V_R = 30 \text{ V}$		-	28	-	
Poverse recovery time		$I_F = 0.5 \text{ A}, I_R = 1 \text{ A}, I_{rr} = 0.25 \text{ A}$		-	-	25	
Reverse recovery time t _{rr}	L _{rr}	T _J = 25 °C		-	22	-	ns
		T _J = 125 °C		-	33	-	
Peak recovery current I _{RRM}	1	T _J = 25 °C	$I_F = 6 A$	-	2.4	-	А
	IRRM	T _J = 125 °C	dI _F /dt = 200 A/μs V _R = 160 V	-	5.0	-	A
Reverse recovery charge Q _{rr}	0	T _J = 25 °C		-	27	-	nC
	T _J = 125 °C		-	80	-	110	

THERMAL - MECHANICAL SPECIFICATIONS						
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Maximum junction and storage temperature range	T _J , T _{Stg}		-55	-	175	°C
Thermal resistance, junction to solder pad	R _{thJ-Sp}		-	2.2	3	°C/W
Thermal resistance, junction to ambient	R _{thJA}		-	85	-	C/VV
Approximate weight				0.1		g
Approximate weight			0.0035		oz.	
Marking device		Case style SMPC (TO-277A)		NE	H1	

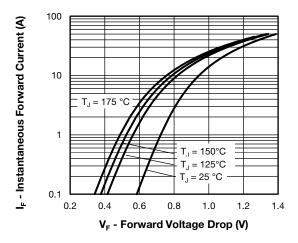


Fig. 1 - Typical Forward Voltage Drop Characteristics

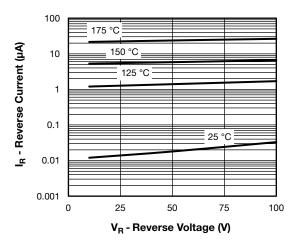


Fig. 2 - Typical Values of Reverse Current vs. Reverse Voltage

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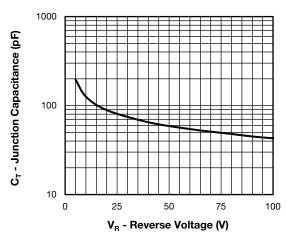


Fig. 3 - Typical Junction Capacitance vs. Reverse Voltage

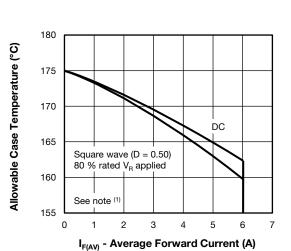


Fig. 4 - Maximum Allowable Case Temperature vs. Average Forward Current

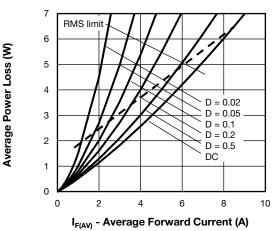


Fig. 5 - Forward Power Loss Characteristics

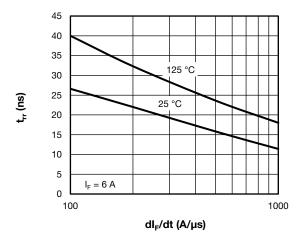


Fig. 6 - Typical Reverse Recovery Time vs. dl_F/dt

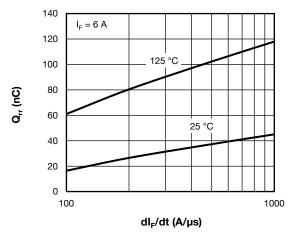


Fig. 7 - Typical Stored Charge vs. dl_F/dt

Note

 $\begin{array}{ll} \text{(1)} \ \ \text{Formula used: } T_C = T_J - (Pd + Pd_{REV}) \times R_{thJC}; \\ Pd = \text{forward power loss} = I_{F(AV)} \times V_{FM} \text{ at } (I_{F(AV)}/D) \text{ (see fig. 5)}; \\ Pd_{REV} = \text{inverse power loss} = V_{R1} \times I_R \text{ (1 - D); } I_R \text{ at } V_{R1} = \text{rated } V_R \\ \end{array}$



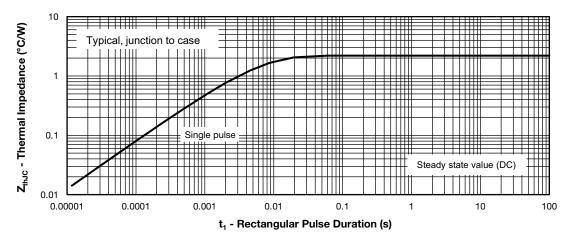


Fig. 8 - Transient Thermal Impedance, Junction to Case

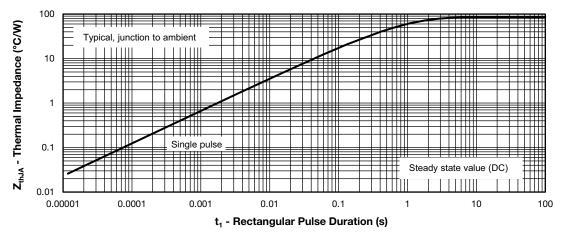
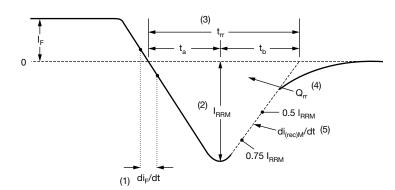


Fig. 9 - Transient Thermal Impedance, Junction to Ambient



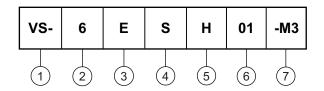
- (1) di_F/dt rate of change of current through zero crossing
- (2) I_{RRM} peak reverse recovery current
- (3) t_{rr} reverse recovery time measured from zero crossing point of negative going I_F to point where a line passing through 0.75 I_{RRM} and 0.50 I_{RRM} extrapolated to zero current.
- (4) Q_{rr} area under curve defined by t_{rr} and I_{RBM}
 - $Q_{rr} = \frac{t_{rr} x I_{RRM}}{2}$
- (5) di_{(rec)M}/dt peak rate of change of current during t_b portion of t_{rr}

Fig. 10 - Reverse Recovery Waveform and Definitions



ORDERING INFORMATION TABLE

Device code



Vishay Semiconductors product

2 - Current rating (6 = 6 A)

Circuit configuration:

E = single diode

4 - S = SMPC package

5 - Process type,

H = hyperfast recovery

6 - Voltage code (01 = 100 V)

7 - -M3 = halogen-free, RoHS-compliant, and terminations lead (Pb)-free

ORDERING INFORMATION (Example)					
PREFERRED P/N	QUANTITY PER REEL	MINIMUM ORDER QUANTITY	PACKAGING DESCRIPTION		
VS-6ESH01-M3/86A	1500	1500	7" diameter plastic tape and reel		
VS-6ESH01-M3/87A	6500	6500	13" diameter plastic tape and reel		

LINKS TO RELATED DOCUMENTS				
Dimensions	www.vishay.com/doc?95570			
Part marking information	www.vishay.com/doc?95565			
Packaging information	www.vishay.com/doc?88869			
SPICE model	www.vishay.com/doc?96111			



TO-277A (SMPC)

DIMENSIONS in inches (millimeters)





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Vishay

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